Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"6703707".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/08 17:37
L2	28203	resin with (bump ball)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/08 18:04
L3	1	1 and "21"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/08 17:38
L4	1	1 and 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/08 17:46
L5	6162	rab	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/08 17:46
L6	34346	5 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/08 17:46
L7	8508	(semiconductor chip die ic (integrated adj circuit)) same 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/08 17:47
L8	482	(heat with (radiate radiating radiation radiated spreader plate plating sink slug metal dissipating dissipated dissipate dissippation)) same 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/08 17:51

L9	5265	resin adj3 (bump ball)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/08 18:04
L10	100	8 and 9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/08 18:04